

# Midterm this Week

- Midterm in lab.
- Duration: 1 hour (2-3pm).
- Material on midterm:
  - Everything from first 4 weeks of class.
  - Thévenin's Theorem & Source Impedance.
  - Impedance of resistors, capacitors, and inductors.
  - Filters (RC,RL,RLC,low-pass,high-pass, bandpass, notch, Chebyshev, Butterworth, etc ...).
  - Basic oscilloscope use, resistor code, etc...
- Midterm will cover design exercises and lab exercises.
- The purpose of the midterm is to consolidate passive analog linear circuitry before we move onto non-linear devices.

# Diodes

*a non-linear circuit element*



- 2-terminal **quantum** device
- ***A diode only conducts in one direction !!!***
- **Non-linear** → **Ohm's Law** doesn't apply !
  - There is no simple  $Z_{diode}$  formula !
  - **Thevenin's theorem** doesn't apply !
- **Calculus:** you can linearize a function/system in the vicinity of some  $V_0$  or  $I_0$ .
  - **Ohm's law**,  $Z_{diode}$ , and **Thevenin's theorem** can only be used locally around some value of  $V_0$  and  $I_0$ .
  - i.e. you can still write down a differential equation for your circuit (i.e. Kirchhoff's loop and junction laws are still valid).

# Intro to Semiconductors

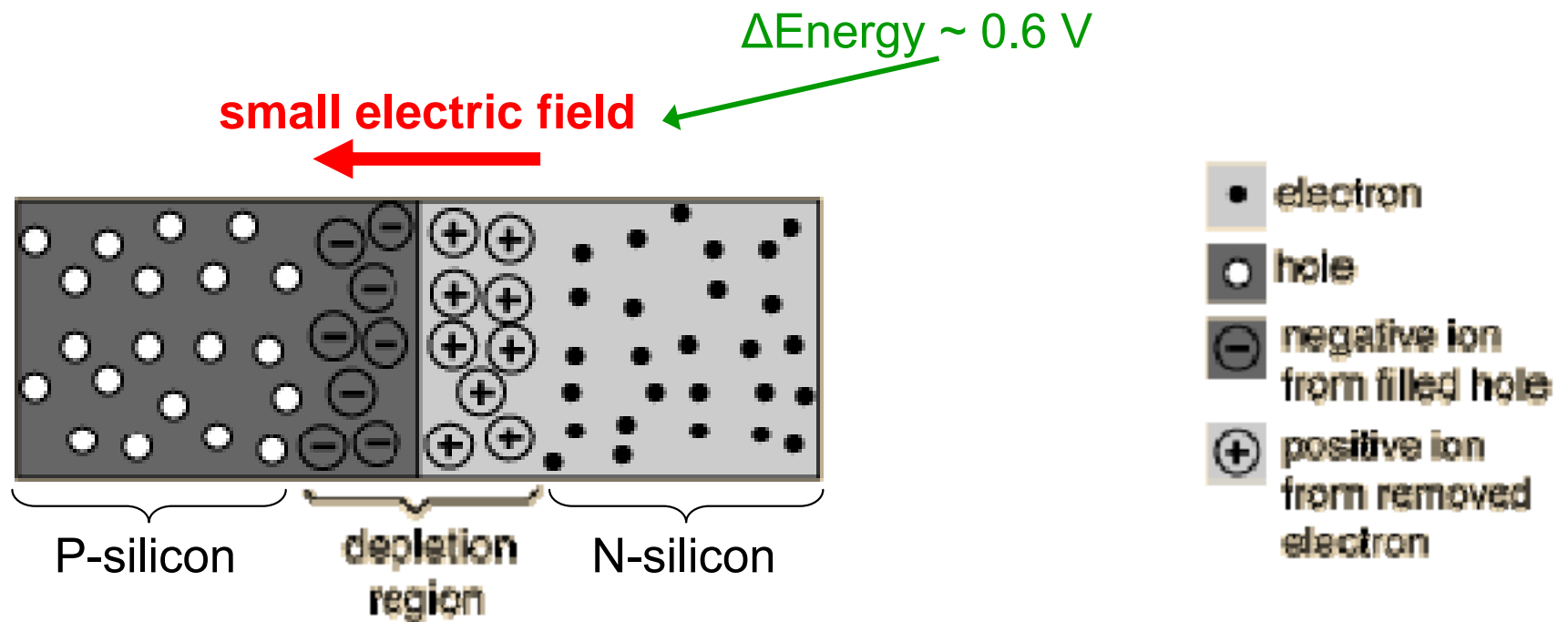
- Semiconductors have a modest resistivity:
- Normally we think of electrons moving in a circuit
- In a semiconductor things are a little different
  - We think of either holes or electrons.
    - Holes (+ charge)
    - Electrons (- charge)

Material	Resistivity
Copper	$1.70 \times 10^{-8} \Omega \cdot m$
Silicon	$6400 \Omega \cdot m$
Rubber	$\sim 10^{13} \Omega \cdot m$

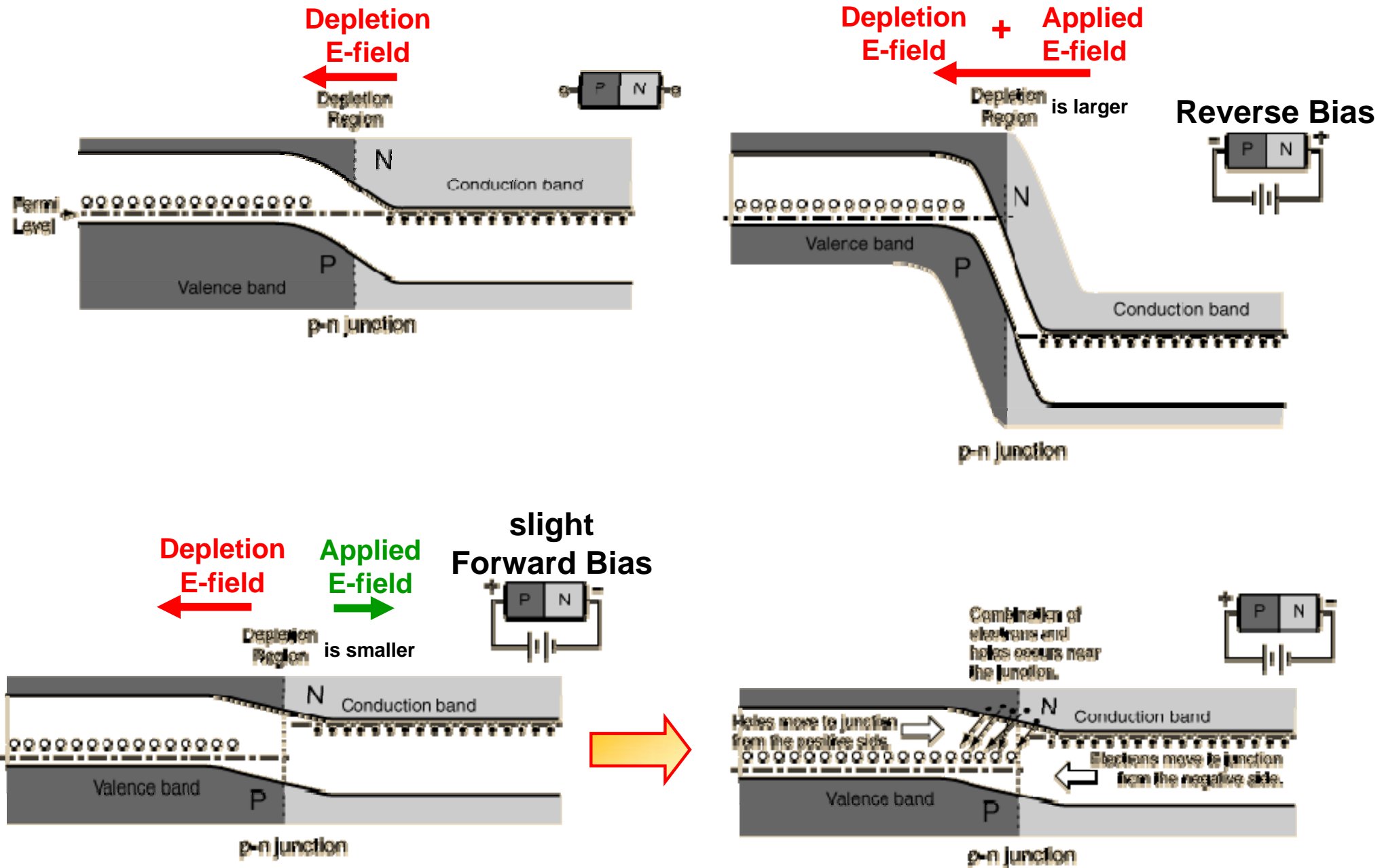


# The PN junction

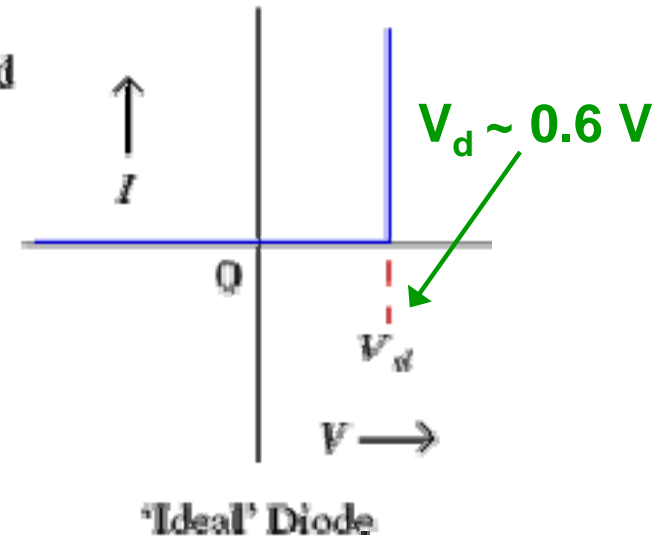
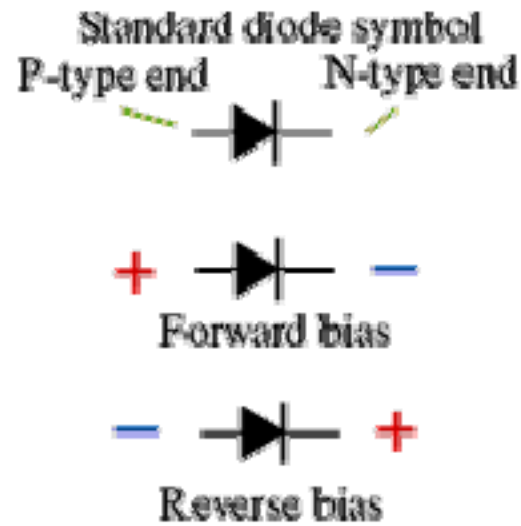
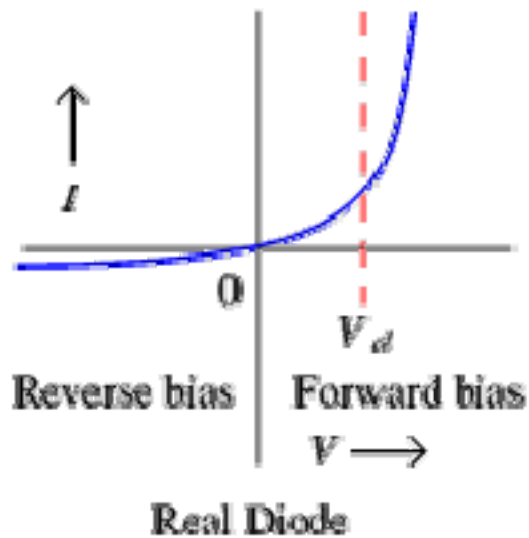
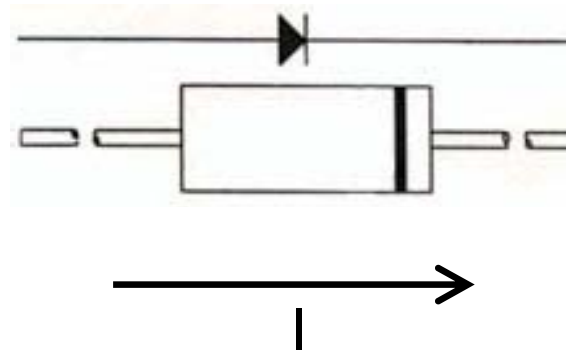
- Made from differently doped silicon
  - N region has more electrons
  - P region had more holes
- At the **PN junction** the holes & electrons recombine to form a small insulating **depletion region**.



# How a diode works



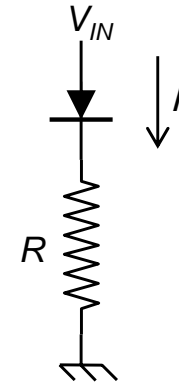
# Diode: I-V characteristic curve I



# Diode: I-V characteristic curve II

## ➤ *Simple model*

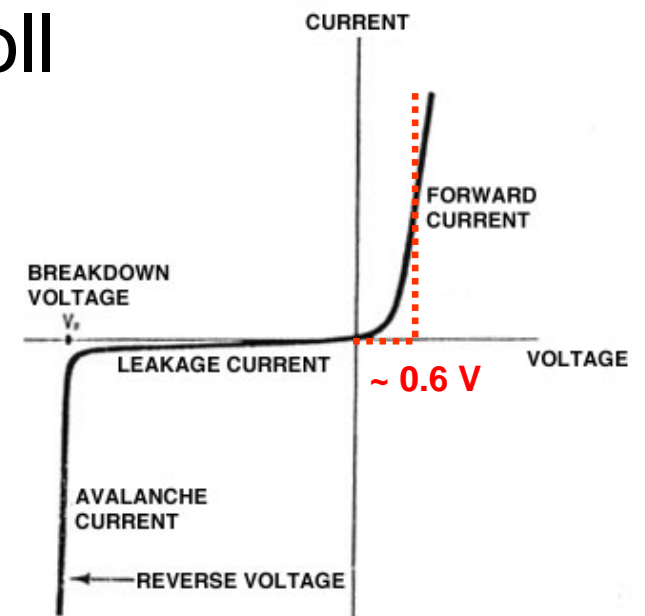
- Current can only flow in one direction.
- A 0.6V “diode drop” when conducting.
- $IR = V_{IN} - 0.6\text{ V}$
- Useful for designing circuits.



Current only flows in the direction of the arrow.

## ➤ More complete model: Ebers-Moll equation.

- Not so useful for designing circuits.



- A little negative is OK  
A lot is “bad” → smoke!!!!

# Diode Spec Sheet



January 2007

1N/FDLL 914/A/B / 916/A/B / 4148 / 4448

Small Signal Diode



DO-35

Cathode is denoted with a black band



LL-34

THE PLACEMENT OF THE EXPANSION GAP HAS NO RELATIONSHIP TO THE LOCATION OF THE CATHODE TERMINAL.

DEVICE	1ST BAND	2ND BAND
FDLL914	BLACK	BROWN
FDLL914A	BLACK	GRAY
FDLL914B	BROWN	BLACK
FDLL915	BLACK	RED
FDLL915A	BLACK	WHITE
FDLL915B	BROWN	BROWN
FDLL4148	BLACK	BROWN
FDLL4448	BROWN	BLACK

-1st band denotes cathode terminal and has wider width

### Absolute Maximum Ratings\* $T_J=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
$V_{RRM}$	Maximum Repetitive Reverse Voltage	100	V
$I_O$	Average Rectified Forward Current	200	mA
$I_F$	DC Forward Current	300	mA
$I_{FRM}$	Recurrent Peak Forward Current	400	mA
$I_{FSM}$	Non-repetitive Peak Forward Surge Current		
	Pulse Width = 1.0 second	1.0	A
	Pulse Width = 1.0 microsecond	4.0	A
$T_{STG}$	Storage Temperature Range	-65 to +200	$^{\circ}\text{C}$
$T_J$	Operating Junction Temperature	175	$^{\circ}\text{C}$

\* These ratings are limiting values above which the serviceability of the diode may be impaired.

#### NOTES:

- 1) These ratings are based on a maximum junction temperature of 200 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Thermal Characteristics

Symbol	Parameter	Max.	Units
		1N/FDLL 914/A/B / 4148 / 4448	
$P_D$	Power Dissipation	500	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	300	$^{\circ}\text{C}/\text{W}$

1N/FDLL 914/A/B / 916/A/B / 4148 / 4448 Small Signal Diode



# Diode Spec Sheet

1NFDLL 914/A/B / 916/A/B / 4148 / 4448 Small Signal Diode

## Electrical Characteristics\* T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V <sub>R</sub>	Breakdown Voltage	I <sub>R</sub> = 100µA	100		V
		I <sub>R</sub> = 5.0µA	75		V
V <sub>F</sub>	Forward Voltage	1N914B/4448 I <sub>F</sub> = 5.0mA	620	720	mV
		1N916B I <sub>F</sub> = 5.0mA	630	730	mV
		1N914/916/4148 I <sub>F</sub> = 10mA		1.0	V
		1N914A/916A I <sub>F</sub> = 20mA		1.0	V
		1N916B I <sub>F</sub> = 20mA		1.0	V
		1N914B/4448 I <sub>F</sub> = 100mA		1.0	V
I <sub>R</sub>	Reverse Leakage	V <sub>R</sub> = 20V		25	nA
		V <sub>R</sub> = 20V, T <sub>A</sub> = 150°C		50	µA
		V <sub>R</sub> = 75V		5.0	µA
C <sub>T</sub>	Total Capacitance	V <sub>R</sub> = 0, f = 1.0MHz		2.0	pF
		V <sub>R</sub> = 0, f = 1.0MHz		4.0	pF
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 10mA, V <sub>RR</sub> = 5.0V (500mA) I <sub>rr</sub> = 1.0mA, R <sub>L</sub> = 100Ω		4.0	ns

\*Non-recurrent square wave PW = 8.3ms

## Typical Characteristics

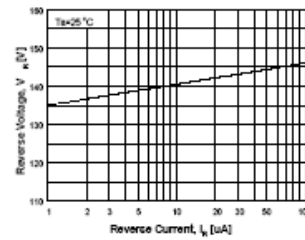


Figure 1. Reverse Voltage vs Reverse Current  
BV - 1.0 to 100µA

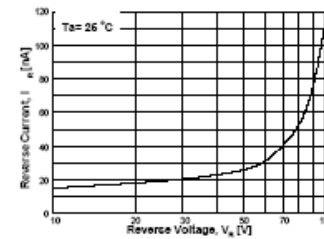


Figure 2. Reverse Current vs Reverse Voltage  
IR - 10 to 100V

GENERAL NOTE: The Reverse Current of a diode will approximately double for every 10°C increase in Temperature.

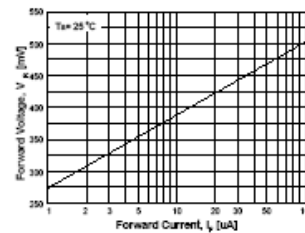


Figure 3. Forward Voltage vs Forward Current  
VF - 1 to 100µA

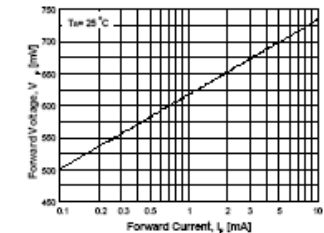


Figure 4. Forward Voltage vs Forward Current  
VF - 0.1 to 10mA

# Diode Spec Sheet

1NFDLL 914/A/B / 916/A/B / 4148 / 4448 Small Signal Diode

## Typical Characteristics (Continued)

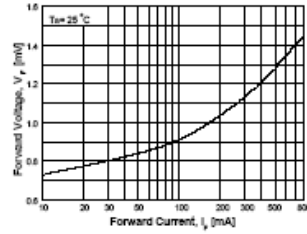


Figure 5. Forward Voltage vs Forward Current  
VF - 10 to 800mA

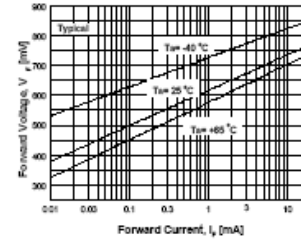


Figure 6. Forward Voltage vs Ambient Temperature  
VF - 0.01 - 20 mA (-40 to +65°C)

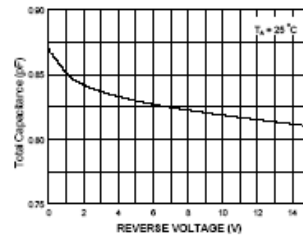


Figure 7. Total Capacitance

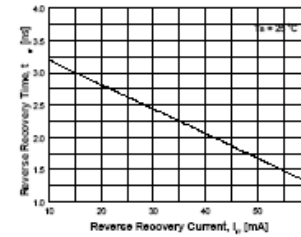


Figure 8. Reverse Recovery Time vs Reverse Recovery Current  
IF = 10mA, IR = 1.0 mA, RREP = 100 Ohms

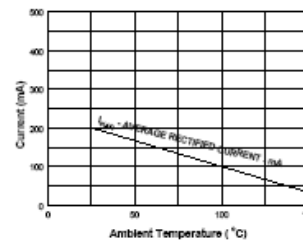


Figure 9. Average Rectified Current ( $I_{R(AV)}$ )  
vs Ambient Temperature ( $T_A$ )

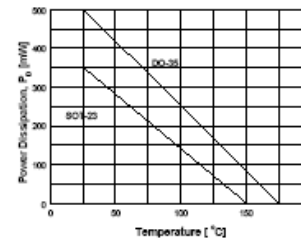


Figure 10. Power Derating Curve

# Diode Spec Sheet



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Rev. 122

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# Applications

- Circuit Protection
- Rectification
  - half wave rectifier
  - full wave rectifier
  - Power Supplies
- Frequency manipulation
  - Frequency multiplier
  - Mixers

# Fourier Transform (FFT) of Full Wave Rectifier

Fourier space representation of rectified output

